

July 18, 2003

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile     Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Continuation of**  
Serial No.: 09/557,395 4/24/00  
SHAU-LIN SHUE, MING-HSING TSAI  
METHOD FOR INTEGRATING LOW-K MATERIALS IN  
SEMICONDUCTOR FABRICATION

**PRELIMINARY AMENDMENT**

Dear Sir:


This is a preliminary amendment for the above referenced Continuation  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on July 21, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date

 7/21/03

June 27, 2003

To: Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N. Y. 1.2603

Subject:

Continuation of		
Serial No.:	09/557,395	Filing Date: 04/24/00
Inventor:	Shue et al.	
Title:	Method for Integrating Low-K Materials in Semiconductor Fabrication	
Art Unit:	2812	Examiner: Pham, Thanhha
Attorney Docket:	TSMC99-132CC	

### PRELIMINARY AMENDMENT

Dear Sirs:


This is a preliminary amendment for the above referenced Continuation Patent Application. Please amend the above-identified application for patent as follows.

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal

Service as first class mail in an envelope addresses to: Commissioner of Patents  
P.O. Box 1450, Alexandria, VA 22313-1450, on

JULY 21, 2003

Signature/Date  7/21/03